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(71) Applicant: ADVANCED MICRO DEVICES, INC. [US/US]; One AMD Place, Mail Stop 68, P.O. Box 3453, Sunnyvale, CA 94088-3453 (US).

(72) Inventors: SONDERMAN, Thomas, J.; 16010 Braesgate Drive, Austin, TX 78717 (US). PASADYN, Alexander, J.; 8717 Dandelion Trail, Austin, TX 78745 (US). BODE, Christopher, A.; 4700 Staggerbrush Road, #738, Austin, TX 78749 (US).

(74) Agent: DRAKE, Paul, S.; Advanced Micro Devices, Inc., 5204 East Ben White Boulevard, Mail Stop 562, Austin, TX 78741 (US).

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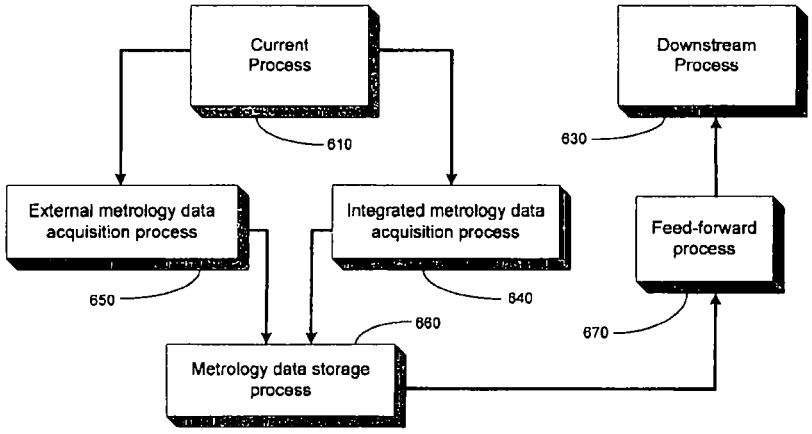
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(54) Title: METHOD AND APPARATUS FOR UTILIZING INTEGRATED METROLOGY DATA AS FEED-FORWARD DATA



(57) Abstract: A method and an apparatus for performing feed-forward correction during semiconductor wafer (105) manufacturing. A first process on a semiconductor wafer (105) is performed. Integrated metrology data related to the first process of the semiconductor wafer (105) is acquired. An integrated metrology feed-forward process is performed based upon the integrated metrology data, the integrated metrology feed-forward process comprising identifying at least one error on the semiconductor wafer (105) based upon the integrated metrology data related to the first process of the semiconductor wafer (105) and performing an adjustment process to a second process to be performed on the wafer to compensate for the error. The second process on the semiconductor wafer (105) is performed based upon the adjustment process.

WO 03/044851 A3

ACTION

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